

6 5 4 3 2 1

D

C

B

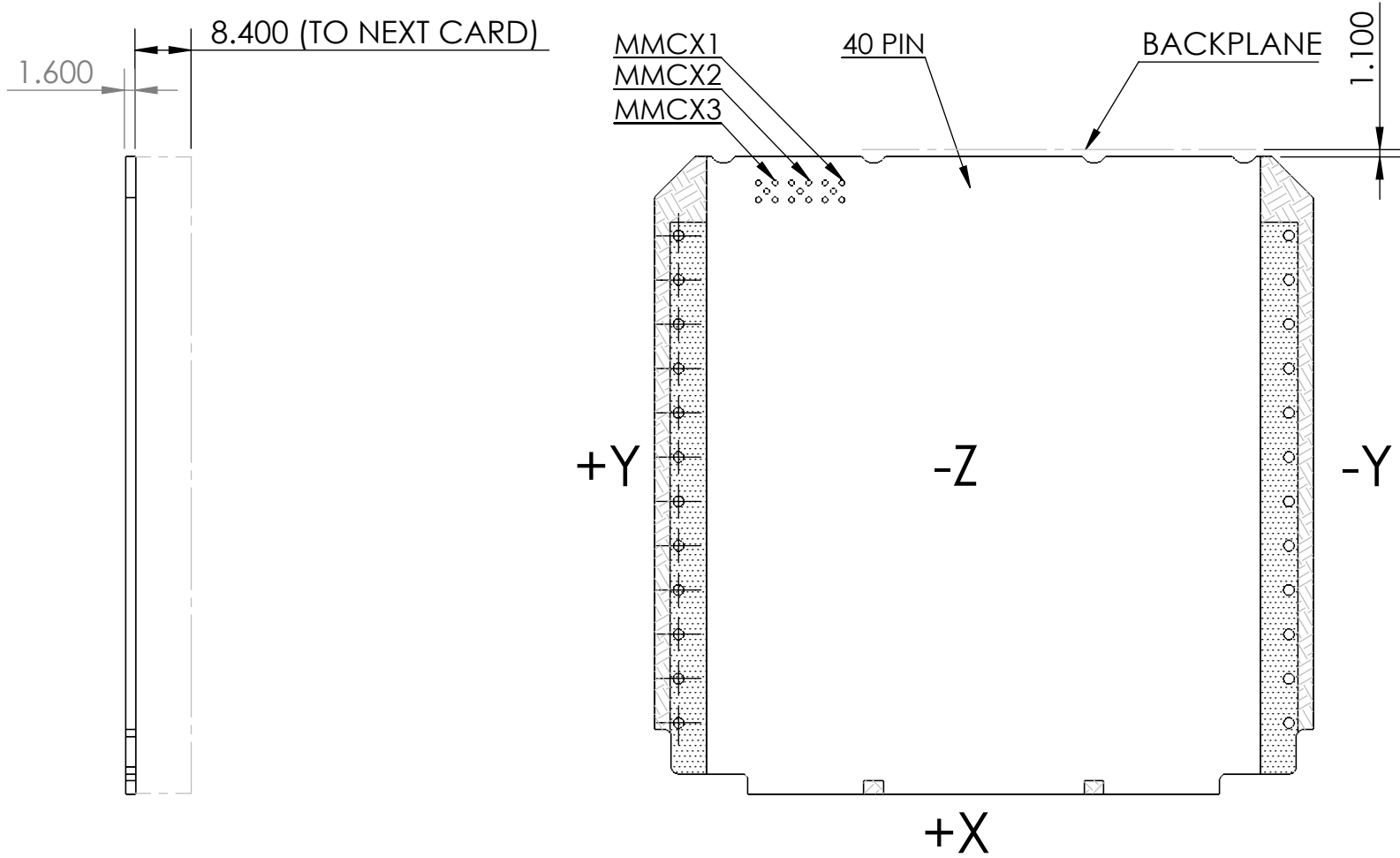
A


D

C

B

A

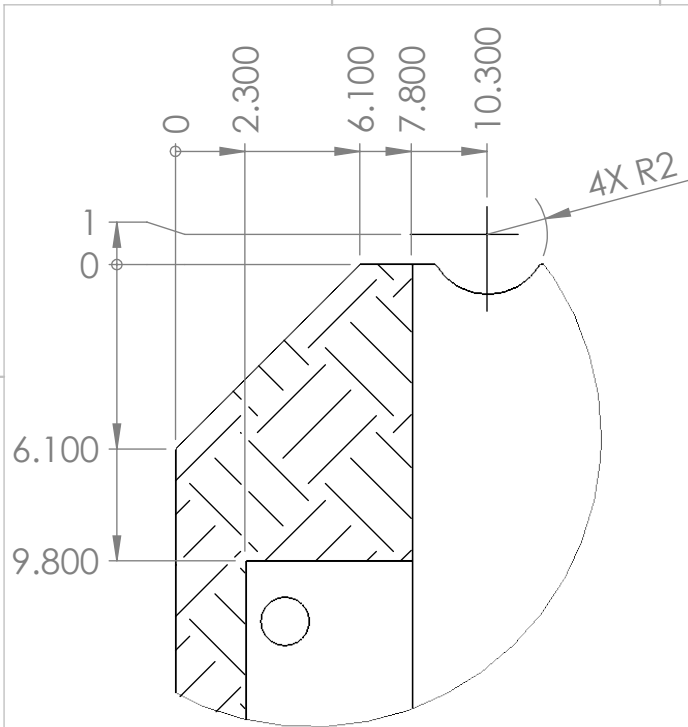


	DRAWN	NAME Joe S.	DATE 2017-3-31	Description: The generic board layout for OreSat
	CHECKED	--		
	ENG APPR.	--		
	MFG APPR.	--		
COMMENTS: RECOMMENDED HEIGHT: <4 mm ABOVE/BELOW CARD				DWG. NO. --
REV 0.5		SIZE A	SCALE: 1:1 SHEET 2 OF 7	

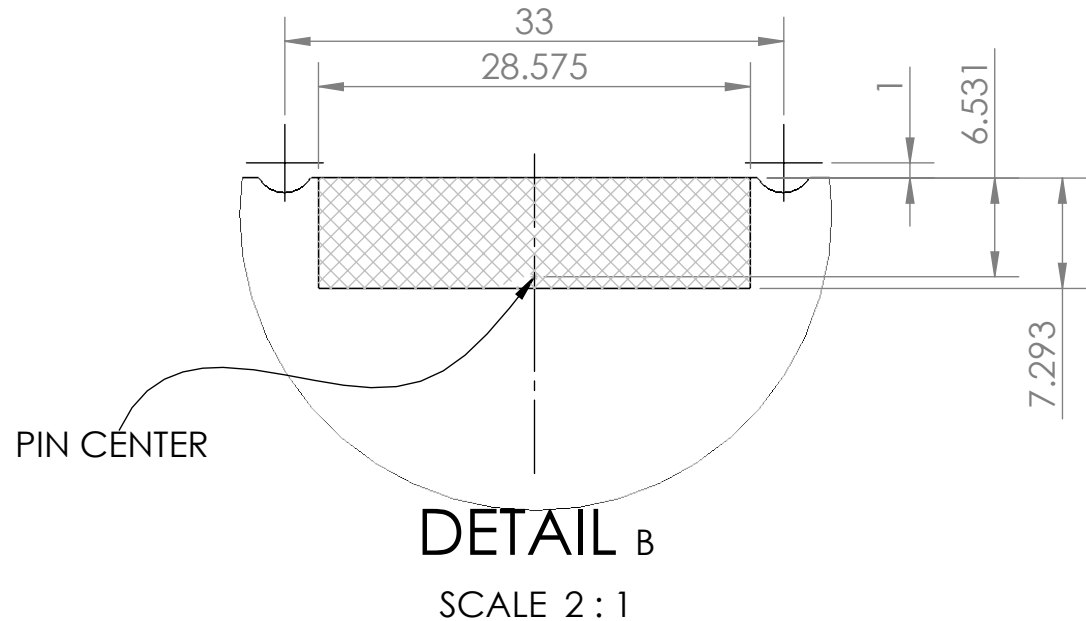
UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN **MILLIMETERS**
TOLERANCES:
FRACTIONAL ± BEND ±
TWO PLACE DECIMAL ±.01
THREE PLACE DECIMAL ±.001

MATERIAL
FR4
FINISH
--
Weight
DO NOT SCALE DRAWING

6 5 4 3 2 1



DETAIL A
SCALE 4 : 1



DETAIL B
SCALE 2 : 1

Note:
The far +X edge of the 30 pin connector's footprint coincides with the edge of its pins.

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN **MILLIMETERS**
TOLERANCES:
ANGULAR EACH \pm BEND \pm
TWO PLACE DECIMAL \pm .01
THREE PLACE DECIMAL \pm .001



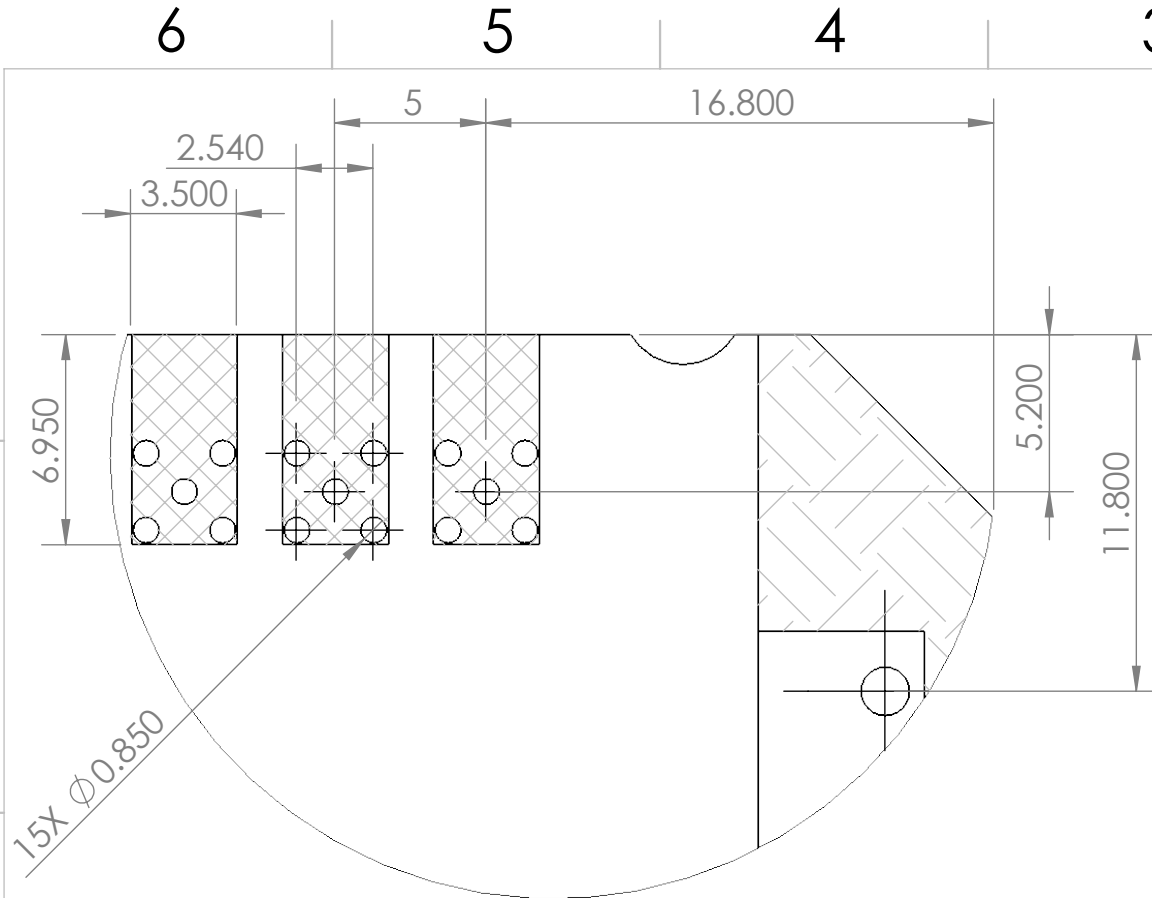
MATERIAL **FR4**
FINISH --
Weight
DO NOT SCALE DRAWING

	NAME	DATE
DRAWN	Joe S.	2017-3-31
CHECKED	--	
ENG APPR.	--	
MFG APPR.	--	

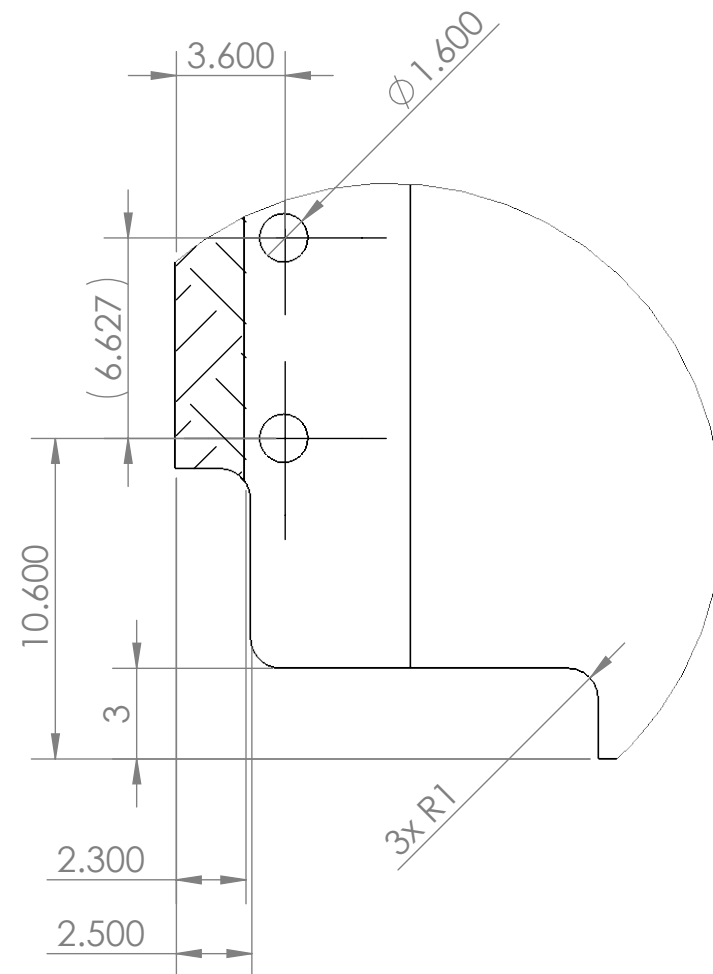
Description:
The generic board layout for OreSat

COMMENTS:
RECOMMENDED HEIGHT:
<4 mm ABOVE/BELOW CARD

DWG. NO.		
--		
REV	SIZE	SCALE: 1:1
0.5	A	SHEET 3 OF 7



DETAIL C
SCALE 4 : 1



DETAIL D
SCALE 4 : 1

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UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN **MILLIMETERS**
TOLERANCES:
FRACTIONAL ± BEND ±
TWO PLACE DECIMAL ±.01
THREE PLACE DECIMAL ±.001

	MATERIAL
	FR4
	FINISH
	--
	Weight
DO NOT SCALE DRAWING	

	NAME	DATE
DRAWN	Joe S.	2017-3-31
CHECKED	--	
ENG APPR.	--	
MFG APPR.	--	

Description:
The generic board layout for
OreSat

COMMENTS:
Spring ping holes shall be
spaced evenly, with 6 to 12
pins per side.

DWG. NO. --		
REV	SIZE	SCALE: 1:1
0.5	A	SHEET 4 OF 7

6

5

4

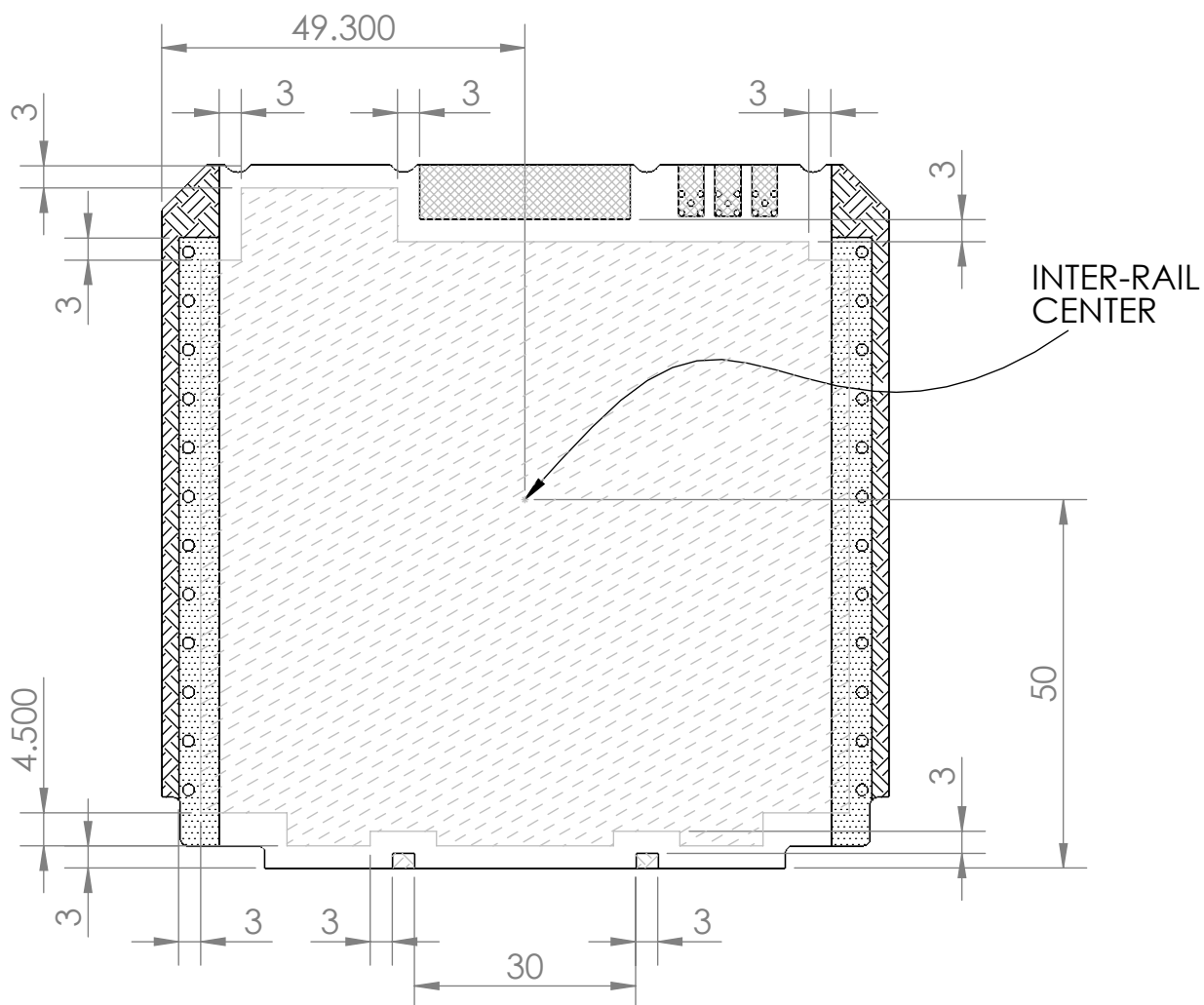
3

2

1



RECOMMENDED BUILD AREA



Note:
Large components should
be placed such that their
total center of mass lies
near the inter-rail center.

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UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN **MILLIMETERS**
TOLERANCES:
FRACTIONAL \pm DECIMAL \pm BEND \pm
TWO PLACE DECIMAL \pm .01
THREE PLACE DECIMAL \pm .001



MATERIAL **FR4**
FINISH --
Weight
DO NOT SCALE DRAWING

	NAME	DATE
DRAWN	Joe S.	2017-3-31
CHECKED	--	
ENG APPR.	--	
MFG APPR.	--	

Description:
The generic board layout for
OreSat

COMMENTS:
RECOMMENDED HEIGHT:
<4 mm ABOVE/BELOW CARD

DWG. NO.		--
REV	SIZE	SCALE: 1:1
0.5	A	SHEET 5 OF 7

6

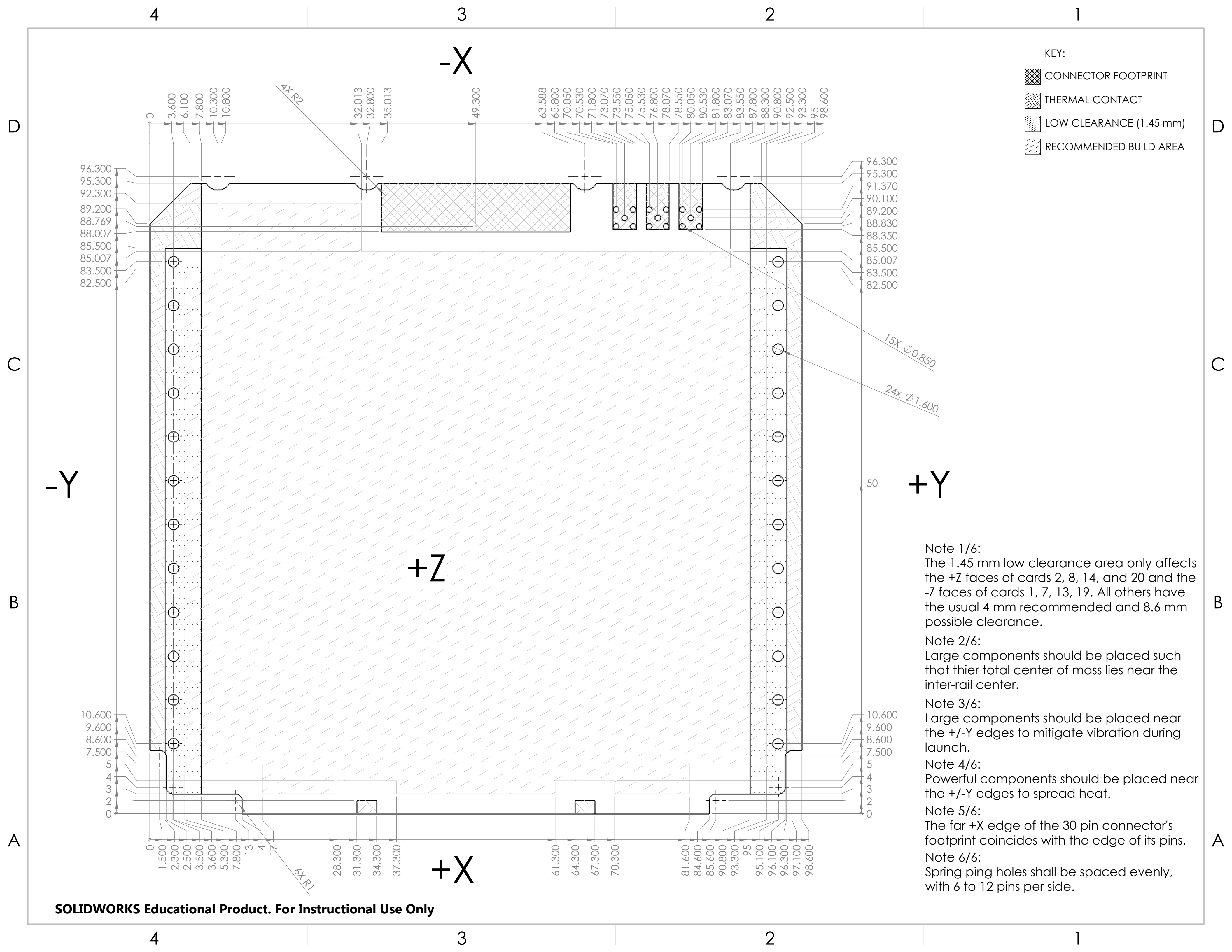
5

4

3

2

1



KEY:

- CONNECTOR FOOTPRINT
- THERMAL CONTACT
- LOW CLEARANCE (1.45 mm)
- RECOMMENDED BUILD AREA

Note 1/6:
The 1.45 mm low clearance area only affects the +Z faces of cards 2, 8, 14, and 20 and the -Z faces of cards 1, 7, 13, 19. All others have the usual 4 mm recommended and 8.6 mm possible clearance.

Note 2/6:
Large components should be placed such that thier total center of mass lies near the inter-rail center.

Note 3/6:
Large components should be placed near the +/-Y edges to mitigate vibration during launch.

Note 4/6:
Powerful components should be placed near the +/-Y edges to spread heat.

Note 5/6:
The far +X edge of the 30 pin connector's footprint coincides with the edge of its pins.

Note 6/6:
Spring ping holes shall be spaced evenly, with 6 to 12 pins per side.